INTELLECTUAL PROPERTY LAW 500 12th Street, Suite 200, Oakland, CA 94607 Telephone: (510) 663-1100 Facsimile: (510) 663-0920 www.beyerlaw.com

FACSIMILE COVER SHEET

December 19, 2006

Receiver:

Examiner Lan Vinh

Group Art Unit 1765

FAX#:

571-273-8300

Sender:

Chereyce R. Brown, Patent Assistant to:

Anna Gavrilova

Our Ref. No.: NOVLP068/NVLS-2818

Application No.: 10/690,084

Re:

Response D

Pages Including Cover Sheet(s): 10

MESSAGE:

Please see the attached documents.

CONFIDENTIALITY NOTE

DEC 1 9 2006

NO. 991 P. 2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Koos et al.

Attorney Docket No.: NOVLP068/NVLS-2818

Application No.: 10/690,084

Examiner: Vinh, Lan

•

Examiner. Viini, Can

Filed: October 20, 2003

Group: 1765

Title: METHOD FOR FABRICATION OF SEMICONDUCTOR INTERCONNECT STRUCTURE WITH REDUCED

CAPACITANCE, LEAKAGE CURRENT, AND

IMPROVED BREAKDOWN VOLTAGE

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being transmitted by facsimile to fax number 571-273-8300 of the U.S. Patent and

Trademark Office on December 19, 2006

Signed: _

chereyce R. Brown

RESPONSE D

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

This is in response to the non-final Office Action mailed November 30, 2006.

Listing of claims begins on page 2 of this paper.

Remarks begin on page 9 of this paper.